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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/073,106	02/12/2002	Tsuyoshi Yamamoto	020154	3709	
38834	7590 05/23/2006		EXAMINER		
WESTERMAN, HATTORI, DANIELS & ADRIAN, LLP			KIM, PAUL D		
SUITE 700	ECTICUT AVENUE, NW		ART UNIT	PAPER NUMBER	
WASHINGTON, DC 20036			3729		
			DATE MAILED: 05/23/2006	DATE MAILED: 05/23/2006	

Please find below and/or attached an Office communication concerning this application or proceeding.

•		Application No.	Applicant(s)
Office Action Summary		10/073,106	YAMAMOTO ET AL.
		Examiner	Art Unit
		Paul D. Kim	3729
Period fo	The MAILING DATE of this communication app or Reply	ears on the cover sheet with the c	orrespondence address
A SH WHIC - Exte after - If NC - Failu Any	ORTENED STATUTORY PERIOD FOR REPLY CHEVER IS LONGER, FROM THE MAILING DANSIONS of time may be available under the provisions of 37 CFR 1.13 SIX (6) MONTHS from the mailing date of this communication. Operiod for reply is specified above, the maximum statutory period we are to reply within the set or extended period for reply will, by statute, reply received by the Office later than three months after the mailing ed patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be tim vill apply and will expire SIX (6) MONTHS from , cause the application to become ABANDONE	N. nely filed the mailing date of this communication. D (35 U.S.C. § 133).
Status			
2a) 🗌	Responsive to communication(s) filed on <u>09 M</u> . This action is FINAL . 2b) This Since this application is in condition for allowar closed in accordance with the practice under E	action is non-final. nce except for formal matters, pro	
Disnositi	ion of Claims		
5)□ 6)⊠ 7)⊠ 8)□	Claim(s) 1-4 and 20 is/are pending in the application of the above claim(s) is/are withdraw Claim(s) is/are allowed. Claim(s) 1-4 is/are rejected. Claim(s) 20 is/are objected to. Claim(s) are subject to restriction and/orders and/orders.	vn from consideration.	
Applicati	ion Papers		
10)	The specification is objected to by the Examine The drawing(s) filed on is/are: a) access Applicant may not request that any objection to the Replacement drawing sheet(s) including the correction The oath or declaration is objected to by the Example 2.	epted or b) objected to by the liderawing(s) be held in abeyance. See ion is required if the drawing(s) is obj	e 37 CFR 1.85(a). jected to. See 37 CFR 1.121(d).
Priority ι	ınder 35 U.S.C. § 119		
a)	Acknowledgment is made of a claim for foreign All b) Some * c) None of: 1. Certified copies of the priority documents 2. Certified copies of the priority documents 3. Copies of the certified copies of the prior application from the International Bureau See the attached detailed Office action for a list of	s have been received. s have been received in Applicati ity documents have been receive I (PCT Rule 17.2(a)).	on No ed in this National Stage
Attachmen	t(s) e of References Cited (PTO-892)	4) ☐ Interview Summary	(PTO_413)
2) 🔲 Notic 3) 🔲 Infor	the of Draftsperson's Patent Drawing Review (PTO-948) mation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) r No(s)/Mail Date	Paper No(s)/Mail Da	

DETAILED ACTION

This office action is a response to the after final amendment filed on 5/9/2006.

Comments

1. Upon further consideration, examiner hereby withdraws the last final office action mailed on 2/9/2006. In view of found prior art and the request for consideration, the finality mailed on 2/9/2006 is hereby withdrawn.

Claim Rejections - 35 USC § 103

- 2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1-4 are rejected under 35 U.S.C. 103(a) as being unpatentable over Nishida (US PAT. 6,981,317) in view of Kobayashi et al. (JP 57188833 A).

Nishida teaches a process of mounting electronic component comprising steps of: placing an electronic component (1) on a substrate (4) with a solid support (6) interposed between the electronic component and the substrate so as to space a terminal conductor (2) of the electronic component from a corresponding terminal pad (5) on the substrate as shown in Fig. 8B; and melting the solid support so as to move down the electronic component toward the substrate, thereby contacting the terminal

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conductor with the conductive bonding material melting on the corresponding terminal pad as shown in Fig. 8C (see also col. 13, line 58 to col. 14, line 16).

As per claim 2 the solid support of Nishida is made of the thermosetting resin, which has a higher melting point than the conductive bonding material (such as solder material, which is well known in the art.

As per claim 4 the thermosetting resin used as the solid support has an adherent property.

However, Nishida does not teach melting the conductive bonding material on the terminal pad prior to contact the terminal conductor with the conductive bonding material. Kobayashi et al. teach a connecting method such that a conductive bonding material (2) is heated to be the melted conductive bonding material (5) before the material to be connected as shown if Figs. 1-2 in order to improve the strength of bonding between the electronic component and the substrate (see also abstract). Therefore, it would have been obvious at the time the invention was made to a person having ordinary skill in the art to modify a mounting process of Nishida by melting the conductive bonding material on the terminal pad before the material to be connected as taught by Kobayashi et al. in order to improve the strength of bonding between the electronic component and the substrate.

As per claim 3 the conductive bonding material of Kobayashi et al. comprises solder bump.

Allowable Subject Matter

3. Claim 20 is objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

Response to Arguments

4. Applicant's arguments with respect to claims 1-4 and 20 have been considered but are most in view of the new ground of rejection.

Conclusion

5. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Paul D. Kim whose telephone number is 571-272-4565. The examiner can normally be reached on Monday-Friday between 6:00 AM to 2:00 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Peter Vo can be reached on 571-272-4690. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Paul D Kim

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Examiner

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